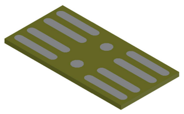
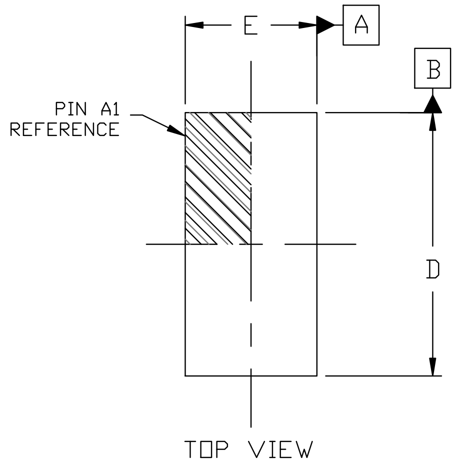
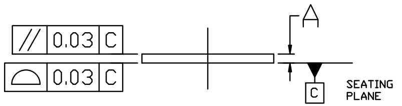


WLCSP10 2.98x1.49x0.1
CASE 567ZG
ISSUE O

DATE 27 MAY 2020



TOP VIEW

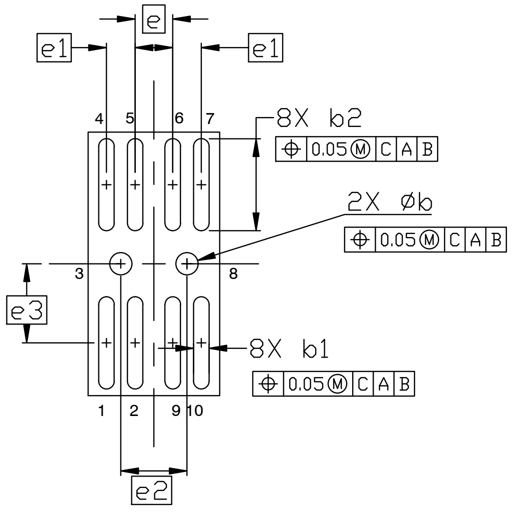


SIDE VIEW

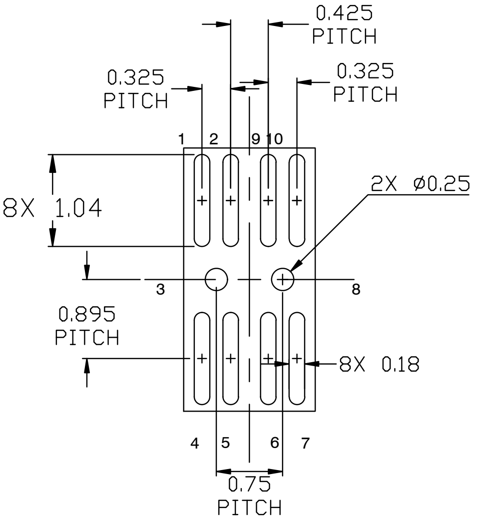
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO ALL PADS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.07	0.10	0.13
b	0.22	0.25	0.28
b1	0.145	0.175	0.205
b2	1.01	1.04	1.07
D	2.95	2.98	3.01
E	1.46	1.49	1.52
e	0.425 BSC		
e1	0.325 BSC		
e2	0.75 BSC		
e3	0.895 BSC		



BOTTOM VIEW



RECOMMENDED
MOUNTING FOOTPRINT*

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

XXXXX▪
AYWZZ▪

XXXX = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week
ZZ = Assembly Lot Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	**WLCSP10 2.98x1.49x0.1**	**PAGE 1 OF 1**